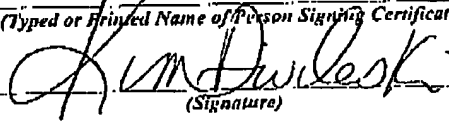


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CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)			Docket No. END920010135US2
Applicant(s): Alcoe et al.			
Application No. 10/665,669	Filing Date 9/18/2003	Examiner Thao, X. Le	Group Art Unit 2814
Invention: THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES			
<p>I hereby certify that this <u>Response to Notice of Non-Compliant Amendment (8 pages)</u></p> <p style="text-align: center;"><small>(Identify type of correspondence)</small></p> <p>is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>703-872-9306</u>)</p> <p>on <u>2/17/2005</u></p> <p style="text-align: center;"><small>(Date)</small></p> <div style="text-align: right; margin-top: 100px;"> <p><u>Kim Dwileski</u></p> <p style="text-align: center;"><small>(Typed or Printed Name of Person Signing Certificate)</small></p> <p></p> <p style="text-align: center;"><small>(Signature)</small></p> </div>			
<p>Note: Each paper must have its own certificate of mailing.</p>			

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/665,669

Applicant(s): Alcoe et al

Filed.: 9/18/2003

Art Unit: 2814

Dkt. No.: END020010135US2

Examiner: Thao X. Le

Title: **THERMALLY ENHANCED LID FOR MULTI-CHIP MODULES**

Honorable Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

This Request for Reconsideration is being filed in response to the Notice of Non-Compliant Amendment (37 CFR 1.121) mailed on February 10, 2005.